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Vasquez et al.

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#### (54) PROCESS CHAMBER MANIFOLD

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(52) U.S. Cl.

USPC ...... **D13/182**; D15/5; D15/122; D23/233

(58) Field of Classification Search

USPC ...... D15/1–7, 122, 135, 136, 199; D23/233; D13/129, 182, 184, 199

CPC . F16K 27/003; F16K 51/02; C23C 16/45544; C23C 16/513; C23C 16/4551; C23C 16/45559; C23C 16/45561; Y10T 137/87684; H05H 1/42

See application file for complete search history.

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#### (57) CLAIM

The ornamental design for a process chamber manifold, as shown and described.

#### DESCRIPTION

FIG. 1 is a top, front, left side isometric view of a process chamber manifold, showing our new design.

FIG. 2 is a bottom, rear, right side isometric view thereof.

FIG. 3 is a left side elevation view thereof.

FIG. 4 is a right side elevation view thereof.

FIG. 5 is a front elevation view thereof.

FIG. 6 is a rear elevation view thereof.

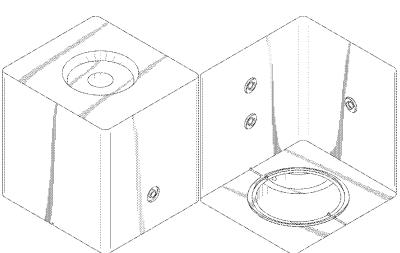
FIG. 7 is a top plan view thereof.

FIG. 8 is a bottom plan view thereof.

FIG. 9 is a cross-sectional view taken along line 9-9 in FIG. 7; and,

FIG. 10 is a cross-sectional view taken along line 10-10 in FIG. 7.

#### 1 Claim, 9 Drawing Sheets



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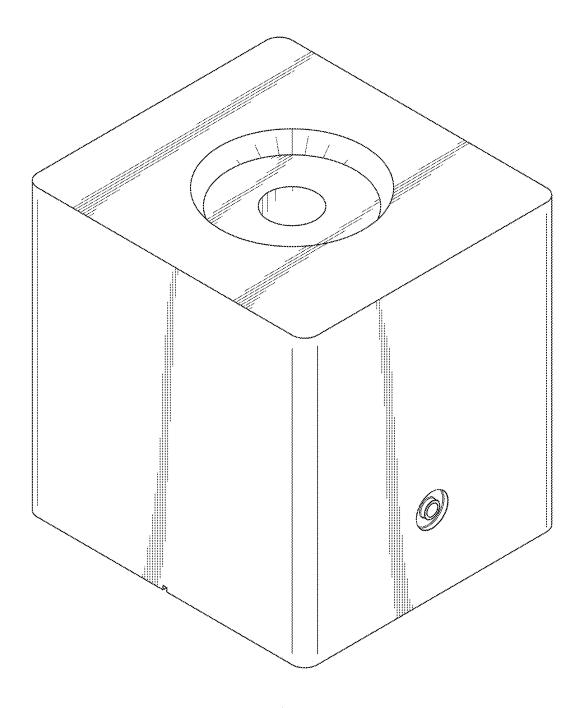


FIG. 1

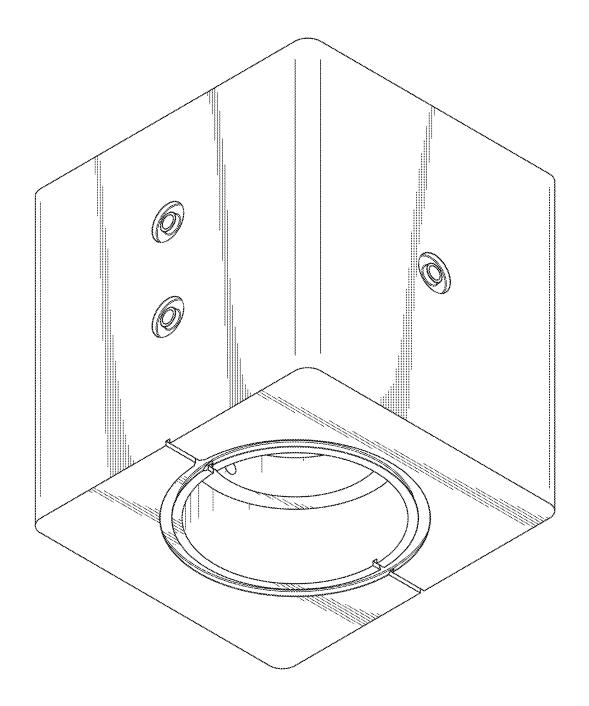


FIG. 2

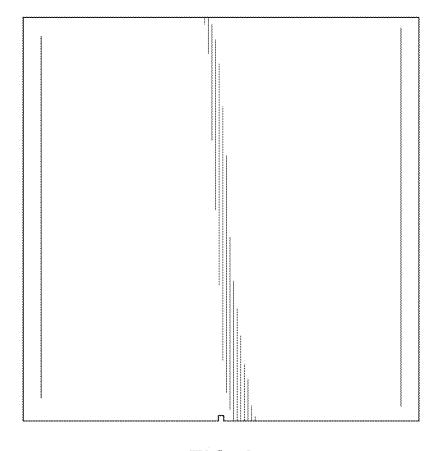


FIG. 3

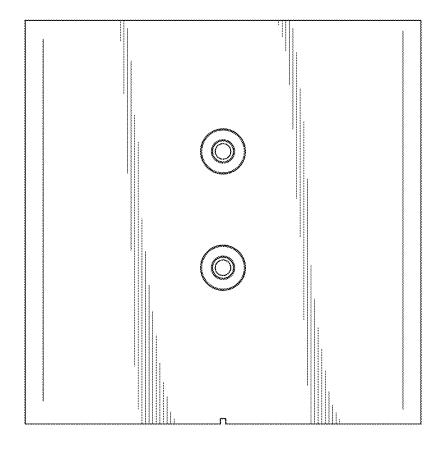


FIG. 4

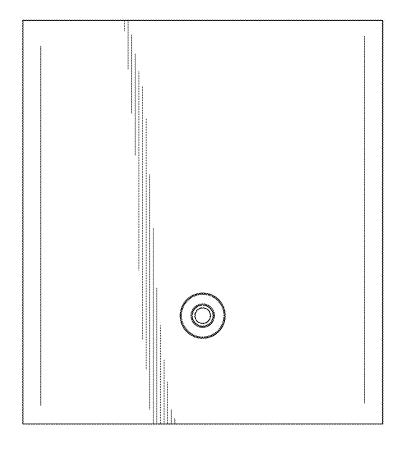


FIG. 5

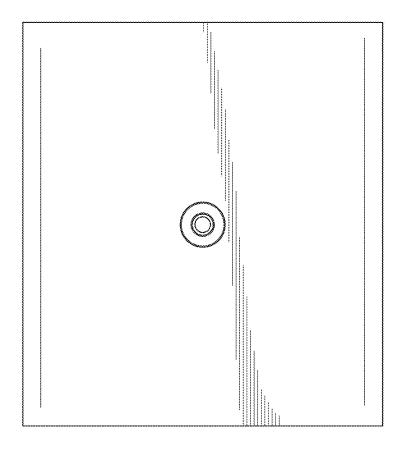
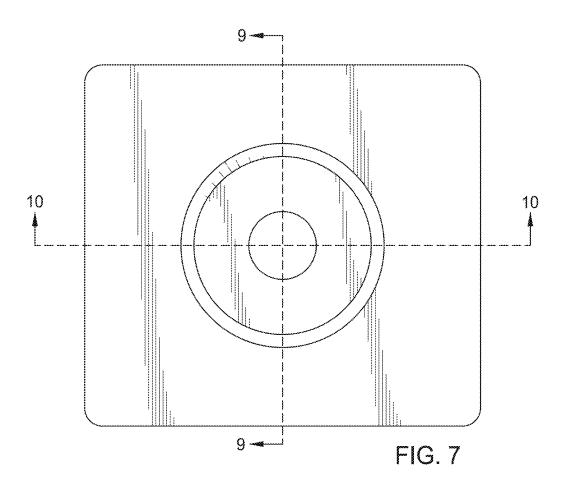


FIG. 6



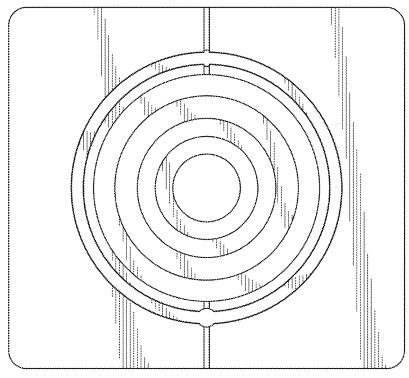


FIG. 8

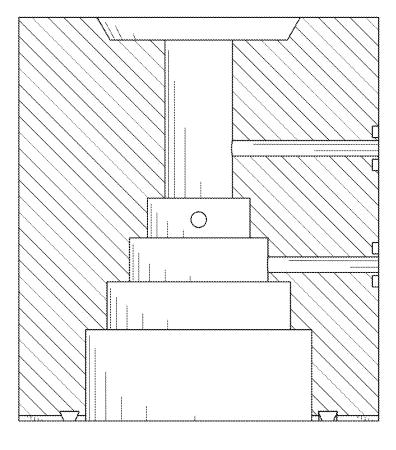


FIG. 9

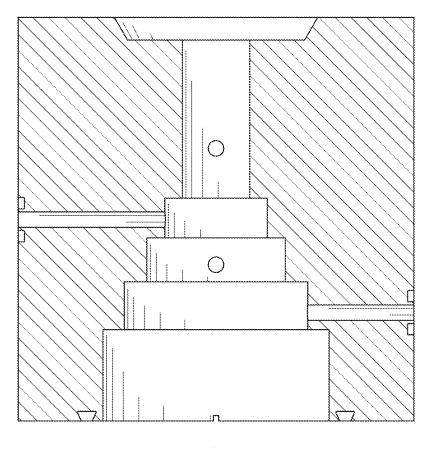


FIG. 10